

**EXPRESS MAIL NO.: EL 477 033 757 US**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Application of: Fukutomi et al.

Group Art Unit: to be assigned

Serial No.: to be assigned  
(Continuation of 10/008,616)

Examiner: to be assigned

Filed: concurrently filed

Attorney Docket No.: 7426-082

For: FABRICATION PROCESS OF  
SEMICONDUCTOR PACKAGE AND  
SEMICONDUCTOR PACKAGE

New York, NY  
January 8, 2002

**PRELIMINARY AMENDMENT**

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

Applicants respectfully request entry of the following amendment and  
remarks in to the file of the above identified application.

IN THE CLAIMS:

Please cancel claims 1-13.

Please add the following new claims:

*Sub B17* 14. (New) A method of producing a substrate for mounting semiconductor

*Q2* devices thereon, said substrate having an insulating supporting member and plural  
sets of wiring, comprising the steps of: